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Contents

vii *Authors*
ix *Conference Committee*

OPTICAL INTERCONNECT SYSTEMS

- 11286 02 **Optical interconnects in enterprise and hyperscale datacenters (Invited Paper)** [11286-1]
- 11286 03 **Market and industrial trends of optical interconnect (Invited Paper)** [11286-2]
- 11286 04 **Intra-satellite optical interconnect space market and technical challenges (Invited Paper)**
[11286-3]
- 11286 05 **Nanoseconds photonic integrated switches for optical data center interconnect systems
(Invited Paper)** [11286-4]
- 11286 06 **Board- and rack-scale optical interconnection architectures for disaggregated data centers
(Invited Paper)** [11286-47]

HYBRID DEVICE INTEGRATION APPROACHES FOR PIC I

- 11286 07 **Photonic plug for scalable silicon photonics packaging (Invited Paper)** [11286-5]

HYBRID DEVICE INTEGRATION APPROACHES FOR PIC II

- 11286 0A **Detachable 1x8 single mode optical interface for DWDM microring silicon photonic
transceivers** [11286-8]

FIBER OPTICS AND MICRO-OPTIC ASSEMBLY

- 11286 0C **Low cutoff G.657-compatible fiber for data center interconnects operating in the 1064 and
1310 nm windows (Invited Paper)** [11286-10]
- 11286 0D **MT-ferrule compatible passive optical coupling for single-mode polymer waveguide in
co-packaged optics (Invited Paper)** [11286-11]
- 11286 0E **Fiber-optic interconnect technologies (Invited Paper)** [11286-12]

11286 OF **Automated PM-fiber array assembly with high-precision four DOF alignment** [11286-13]

11286 OG **Modular lensed-ferrule solution for single-mode fiber connectors** [11286-14]

NOVEL OPTICAL WAVEGUIDE AND INTEGRATED INTERCONNECT TECHNOLOGIES

11286 OH **Bridging the gap: manufacturing optical transceivers in the multibillion-dollar silicon electronics supply chain (Invited Paper)** [11286-15]

11286 OI **Polymer interposer for efficient light coupling into 3 μm silicon-on-insulator waveguides** [11286-16]

11286 OK **Bending loss improvement and twisting loss studies of flexible multimode polymer waveguides** [11286-18]

11286 OL **Novel technology for dispensing liquid polymers of a wide viscosity range on a picoliter scale for photonic applications** [11286-49]

PICS FOR OPTICAL INTERCONNECTS

11286 OM **Integrated silicon photonics for high-volume data center applications (Invited Paper)** [11286-19]

11286 ON **Integrated photonic chip to chip interconnection utilising grating coupler technology** [11286-20]

11286 OO **High-speed and power-efficient beam-steering using 1x16 silicon optical phased array with electro-optic phase shifters** [11286-21]

11286 OP **Building blocks of a scalable and radiation-hardened integrated transmitter unit based on 250 nm SOI** [11286-22]

HYBRID INTEGRATED OPTICAL LINK MODULES I

11286 OQ **Design modifications to an existing high-density mid-board optical engine to survive harsh environments (Invited Paper)** [11286-23]

11286 OR **Short reach, low cost silicon photonic micro-transceivers for embedded and co-packaged system integration (Invited Paper)** [11286-24]

11286 OS **Integrated optical receiver module with demultiplexer for chip-to-chip optical interconnects** [11286-25]

11286 OT **Injection molded low-thermal-expansion multi-fiber ferrule** [11286-26]

OPTICAL INTERCONNECT DEVICES I

- 11286 0U **Low-voltage modulators using thin-film lithium niobate (Invited Paper)** [11286-27]
- 11286 0W **Comparison of three monolithically integrated TIA topologies for 50 Gb/s OOK and PAM4** [11286-29]
- 11286 0X **Strain-engineered group IV light sources for photonic-integrated circuits (Invited Paper)** [11286-30]
- 11286 0Y **A high-performance Echelle grating de-multiplexer based on two stigmatic points and its flat-top solution** [11286-31]

HYBRID INTEGRATED OPTICAL LINK MODULES II

- 11286 10 **Packaging challenges for next-generation high bandwidth opto-electrical switch modules (Invited Paper)** [11286-33]
- 11286 12 **Ring-assisted Mach-Zehnder interferometer switch with multiple rings per switch element** [11286-35]
- 11286 14 **Chip level fiber coupling** [11286-38]

OPTICAL INTERCONNECT DEVICES II

- 11286 17 **Optical interconnects for datacenter links: design and modeling challenges (Invited Paper)** [11286-41]

NANOPHOTONIC TECHNOLOGY FOR OPTICAL INTERCONNECTS

- 11286 1A **High-speed data transmission system using silicon-based optical phased array** [11286-44]
- 11286 1C **Metallic optical benches with stamped micro-mirrors for photonic assemblies and optical interconnects (Invited Paper)** [11286-46]

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